

Title (en)

TOLERANCE COMPENSATION ELEMENT FOR CIRCUIT CONFIGURATIONS

Title (de)

TOLERANZAUSGLEICHSELEMENT FÜR SCHALTBILDER

Title (fr)

ÉLÉMENT DE COMPENSATION DE TOLÉRANCES POUR SCHÉMAS DE CONNEXIONS

Publication

**EP 3622786 A1 20200318 (DE)**

Application

**EP 18734092 A 20180607**

Priority

- DE 102017211330 A 20170704
- EP 2018064983 W 20180607

Abstract (en)

[origin: WO2019007624A1] The invention relates to a tolerance compensation element for circuit configurations having a DCB (direct copper bonded) substrate (1) and a PCB (printed circuit board) (2) and to a circuit configuration having said tolerance compensation element. The invention is characterized in that a tolerance compensation element is positioned in a targeted manner between the DCB substrate (1) and PCB (2) in a gap A (3) for the contact-connection of components (5) on the DCB substrate (1) by means of additive manufacturing and is formed so as to close the gap.

IPC 8 full level

**H01L 23/00** (2006.01); **H05K 1/18** (2006.01); **H05K 3/34** (2006.01); **H05K 3/46** (2006.01)

CPC (source: EP US)

**B33Y 80/00** (2014.12 - EP US); **H01L 24/83** (2013.01 - EP); **H05K 1/186** (2013.01 - EP US); **H05K 3/3485** (2020.08 - EP); **H05K 3/4614** (2013.01 - EP US); **H01L 24/83** (2013.01 - US); **H01L 2224/06181** (2013.01 - EP); **H01L 2224/16225** (2013.01 - EP); **H01L 2224/291** (2013.01 - EP); **H01L 2224/33181** (2013.01 - EP); **H01L 2224/8314** (2013.01 - EP); **H01L 2224/83815** (2013.01 - EP); **H01L 2224/83986** (2013.01 - EP); **H05K 3/3485** (2020.08 - US); **H05K 5/0069** (2013.01 - US); **H05K 2201/10636** (2013.01 - EP); **H05K 2203/0425** (2013.01 - EP); **H05K 2203/107** (2013.01 - EP); **Y02P 10/25** (2015.11 - EP); **Y02P 70/50** (2015.11 - EP)

Citation (search report)

See references of WO 2019007624A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**DE 102017211330 A1 20190110**; CN 110870391 A 20200306; EP 3622786 A1 20200318; US 2020122450 A1 20200423; US 2023189450 A1 20230615; WO 2019007624 A1 20190110

DOCDB simple family (application)

**DE 102017211330 A 20170704**; CN 201880045267 A 20180607; EP 18734092 A 20180607; EP 2018064983 W 20180607; US 201816627529 A 20180607; US 202318167379 A 20230210